

OL-NX3P1107UK

wafer level chip-size package; 4 bumps

10 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	2-7-2012

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
n ₂	actual quantity of termination	-	-	4	-	



2. Legal information

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Date of release: 10 February 2016
